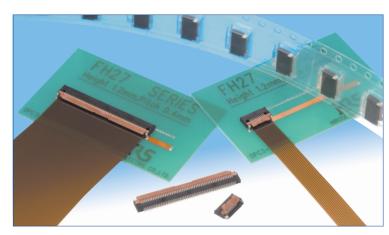


0.4 mm Contact Pitch, 1.2 mm above the board, Flexible Printed Circuit ZIF Connectors

FH 27 Series



Overview

Continuous miniaturization of personal mobile devices created a need for a low profile, high density interconnection system.In the same time, the demand for higher currents and higher reliability Flexible Printed Circuits has also increased. Hirose meets all these challenges with introduction of this connector.

Features

1. Low profile, small PCB mounting area, weight reduction Protruding only 1.2 mm above the board the connector occupies 50% less area than comparable type having contacts spaced on 0.5 mm centers.

Creative design, coupled with high manufacturing capabilities resulted in extremely low weight of the connector.

2. Higher current carrying capacity

Contact spacing of 0.4 mm allows production of wider and simpler pattern of conductive traces on FPC.

3. FPC temporary hold and verification of correct insertion The connector has built-in FPC hold protrusions allowing the tactile feel of the correct FPC insertion and holding it in position before closing of the actuator.

4. Uses standard 0.2 mm thick FPC

5. One-finger operation of the actuator

Proven (in several other Hirose's connectors!) Flip-Lock rotating actuator assures reliable mechanical and electrical connection with FPC, confirming it with a definite tactile feel.

6. Board placement with automatic equipment

Flat top surface and packaging on the tape-and reel allows the use of vacuum nozzles.

Standard reel contains 2,500 connectors.

7. Environmental considerations

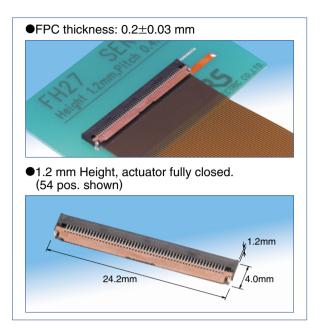
The center cores of the embossed tape reels are made of Styrofoam.

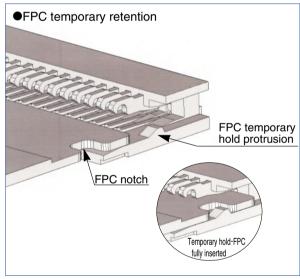
8. Variety of contact positions

Available with 10, 40, 54, 57 and 60 pos.

Applications

Mobile phones, PDA's, digital cameras, digital video cameras, LCD connections, plasma displays (PDP), camera modules and other compact devices requiring Flexible Printed Circuit connections using high reliability ultra-small profile connectors







■Product Specifications

Rating	Rated current 0.4 A DC Rated voltage 40 V AC	Operating temperature range -55°C to +85°C (Note 1) Operating humidity range Relative humidity 90% max. (No condensation)	Storage temperature range -10°C to +50°C (Note 2) Storage humidity range Relative humidity 90% max.
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Recommended FPC Thickness: = 0.2±0.03mm tin-lead plated (Note 3)

Item	Specification	Conditions			
1. Insulation resistance	500 M Ω min.	100 V DC			
2. Withstanding voltage	No flashover or insulation breakdown.	120 V AC /one minute			
3. Contact resistance	100 m ohms max.	1 mA			
	* Including FPC conductor resistance				
4. Durability	Contact resistance: 100 m Ω max.	20 cycles			
(insertion/ withdrawal)	No damage, cracks, or parts dislocation.				
	No electrical discontinuity of 1 μ s or more.	Fraguency 10 to 55 Uz. single amplitude of 0.75 mm, 10 sycle in			
5. Vibration	Contact resistance: 100 m Ω max.	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 10 cycle in			
	No damage, cracks, or parts dislocation.	each of the 3 directions.			
	No electrical discontinuity of 1 μ s. min.	Acceleration of 981 m/s², 6ms duration, sine half-wave			
6. Shock	Contact resistance: 100 m Ω max.				
	No damage, cracks, or parts dislocation.	waveform, 3 cycles / each of 3 axis			
7 Llumaiditu	Contact resistance: 100 m Ω max.				
7. Humidity	Insulation resistance: 50 M Ω min.	96 hours at temperature of 40℃ and humidity of 90% to 95%.RH			
(Steady state)	No damage, cracks, or parts dislocation.				
	Contact resistance: 100 m Ω max.	Temperature: $-55^{\circ}\text{C} \rightarrow +15^{\circ}\text{C}$ to $+35^{\circ}\text{C} \rightarrow +85^{\circ}\text{C} \rightarrow +15^{\circ}\text{C}$ to $+35^{\circ}\text{C}$			
8. Temperature cycle	Insulation resistance: 50 M Ω min.	Time: $30 \rightarrow 2$ to $3 \rightarrow 30 \rightarrow 2$ to 3 (Minutes)			
	No damage, cracks, or parts dislocation.	5 cycles			
9. Resistance to	No defermation of company of esting newformance	Reflow: At the recommended temperature profile			
soldering heat	No deformation of components affecting performance.	Manual soldering: 350℃±5℃ for 5 seconds			

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation.

Note 3: When using FPC with gold plated contact pads the connector contacts must be also gold plated: Select the (05) plating code.

■Materials

Part	Material	Finish	Remarks
Insulator	LCP	Color: Black	UL94V-0
Actuator LCP		Color: Dark brown	
Contacts	Phosphor bronze	Tin-lead plated (Note 3)	
Metal fittings	Phosphor bronze	Tin plated(No-lead)	

■Ordering information

FH27-54S-0.4-SH (05)

0	1 Series name: FH27		Terminal type		
2	No. of contacts		SH: SMT horizontal mounting type		
	Number of contacts: 10, 40, 54, 57, 60	6	Plating code	(05): Gold plated	
8	Contact pitch: 0.4 mm			(51): Tin-lead plated	

●Operation and Precautions

Operation

- 1.FPC insertion procedure. Connector installed on the board.
- 1) Lift up the actuator. Use thumb or index finger.



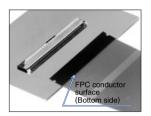
1 Do not apply excessive force or use any type of tool to operate the actuator.

Precautions



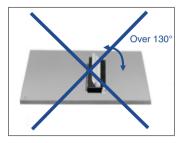


- 2 Fully insert the FPC in the connector parallel to mounting surface, with the exposed conductive traces facing down.

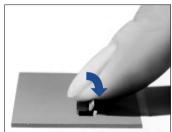




2 The connector will assure reliable performance when the actuator is open to 130° maximum. Do not exceed this angle, as this may cause permanent damage to the connector.



3 Rotate down the actuator until firmly closed. It is critical that the inserted FPC is not moved and remains fully inserted.

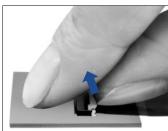


③ Exercise caution when applying upward force to the connected FPC.

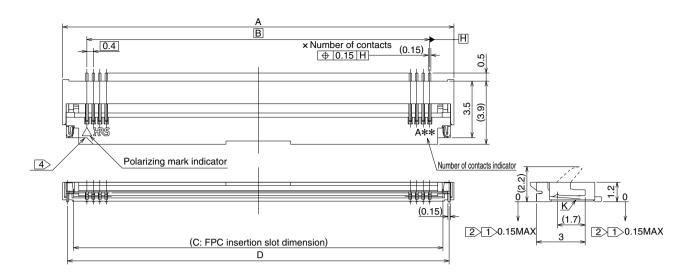


2.FPC removal

1 Lift up the actuator. Carefully withdraw the FPC.



■Connector Dimension



Notes $\boxed{1}$ The coplanarity of each terminal lead is within 0.1.

- 2 The contact terminal lead position indicates the dimension from the K surface, the bottom surface of the insulator body.
- 3 Slight variations in color of the plastic compounds do not affect form, fit or function of the connector.
- 4 Some versions may have material removed from this area. No affect on form, fit or function of the connector.

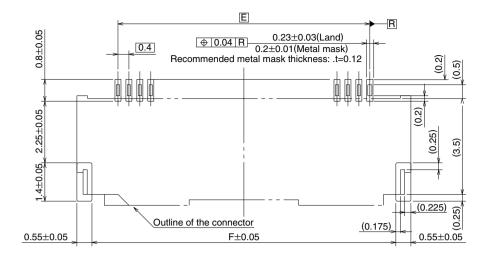
Unit: mm

Part Number	CL No.	Number of Contacts	A	В	С	D
FH27-10S-0.4SH	CL580-0004-0	10	6.6	3.6	5.24	6.0
FH27-40S-0.4SH	CL580-0005-3	40	18.6	15.6	17.24	18.0
FH27-54S-0.4SH	CL580-0001-2	54	24.2	21.2	22.84	23.6
FH27-57S-0.4SH	CL580-0003-8	57	25.4	22.4	24.04	24.8
FH27-60S-0.4SH	CL580-0006-6	60	26.6	23.6	25.24	26.0

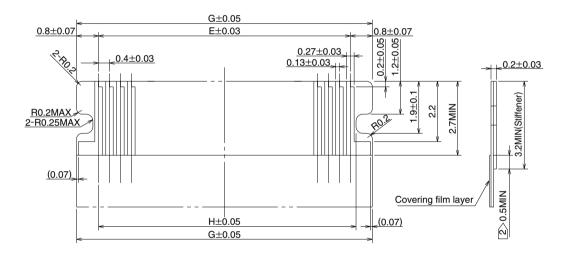
Tape and reel packaging (2,500 pieces/reel).

Order by number of reels.

♠ Recommended PCB mounting pattern and metal mask dimensions



♠ Recommended FPC Dimensions



- 1 Polyamide and thermally hardening adhesive is recommended as the materials for the stiffener.
- 2 Overlap between covering film layer and stiffener is 0.5mm min.

Unit: mm

Part Number	CL No.	Number of Contacts	E	F	G	Н
FH27-10S-0.4SH	CL580-0004-0	10	3.6	5.5	5.2	4.01
FH27-40S-0.4SH	CL580-0005-3	40	15.6	17.5	17.2	16.01
FH27-54S-0.4SH	CL580-0001-2	54	21.2	23.1	22.8	21.61
FH27-57S-0.4SH	CL580-0003-8	57	22.4	24.3	24.0	22.81
FH27-60S-0.4SH	CL580-0006-6	60	23.6	25.5	25.2	24.01

Tape and tape reel packaging (2,500 pieces/reel).

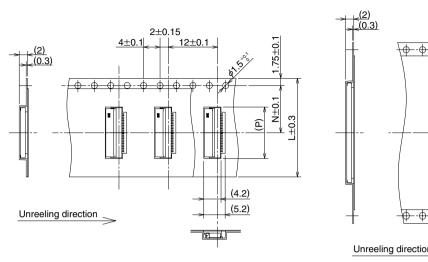
Order by number of reels.

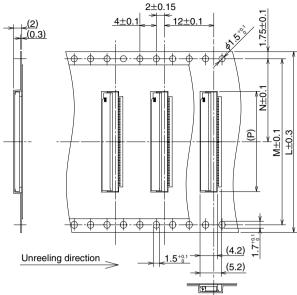
◆Packaging Specification

Embossed Carrier Tape Dimensions

●Tape width up to 24mm.

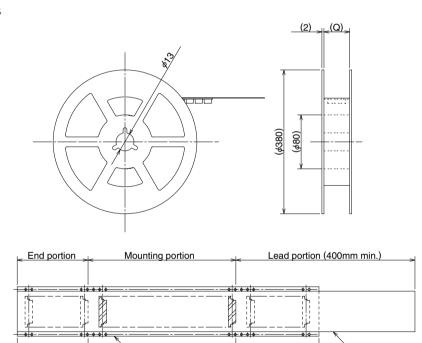
●Tape width 32mm and over.





Top cover tape

●Reel Dimensions



Unit: mm

Part Number	CL No.	Number of Contacts	L	М	N	Р	Q
FH27-10S-0.4SH	CL580-0004-0	10	16.0		7.5	6.9	16.5
FH27-40S-0.4SH	CL580-0005-3	40	32.0	28.4	14.2	18.9	32.5
FH27-54S-0.4SH	CL580-0001-2	54	44.0	40.4	20.2	24.5	44.5
FH27-57S-0.4SH	CL580-0003-8	57	44.0	40.4	20.2	25.7	44.5
FH27-60S-0.4SH	CL580-0006-6	60	44.0	40.4	20.2	26.9	44.5

Embossed carrier tape No connector inserted

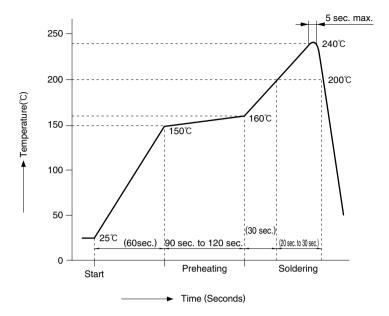
(10 pockets min.)

2,500 pieces per reel.

No connector inserted (10 pockets min.)

♠ Recommended Temperature Profile

●Using Typical Solder Paste



HRS test conditions

Metal mask

Solder method :Reflow, IR/hot air

(Nihon Den-netsu Co., Ltd.'s Part

SENSBY NR-Ⅱ)

Environment :Room air

Solder composition: Paste, 63%Sn/37%Pb

(Senju Metal Industry, Co., Ltd.'s Part Number:

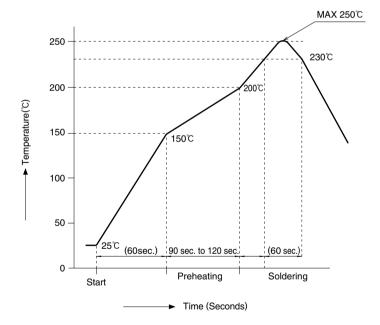
OZ63-201C-50-9)

Test board :Glass epoxy 40mm×100mm×1.6mm thick

Land dimensions:0.23mm×0.8mm

:0.2×0.8×0.12mm thick

Using Lead-free Solder Paste



HRS test condition

Solder method :Reflow, IR/hot air

(Nihon Den-netsu Co., Ltd.'s Part Number:

SENSBY NR-Ⅱ)

Environment :Room air

Solder composition :Paste, 96.5%Sn/3.0%Ag/0.5%Cu

(Senju Metal Industry, Co., Ltd.'s Part Number:

M705-221CM5-42-10.5)

Test board :Glass epoxy 70mm×80mm×1.6mm thick

Land dimensions:0.23mm×08mm

Metal mask :0.2×0.8×0.12mm thick

The temperature profiles shown are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume / thickness and board size / thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

◆FPC Construction (Recommended Specifications)

1. Using Single-sided FPC Thickness (µm) Material Name Material Top side Covering layer film Polyamide 1 mil thick. 25 Cover adhesive 25 Surface treatment Tin-lead plated 5 35 Copper foil Cu 1/2oz Base adhesive 25 Base film Polyamide 1 mil thick 25 Reinforcement material adhesive Thermosetting adhesive 30 Stiffener Polyamide 3 mil thick 75 Total 195 Bottom side

2. Using Double-sided FPC Thickness (µm) Material Name Material Top side Covering layer film Polyamide 1 mil thick 25 25 Cover adhesive Surface treatment Tin-lead plated 5 15 Through-hole copper Cu Copper foil Cu 1/2oz 18 18 Base adhesive Base film Polyamide 1 mil thick 25 Base adhesive 18 Copper foil Cu 1/2oz 18 Cover adhesive 25 25 Covering layer film Polyamide 1 mil thick Reinforcement material adhesive Thermosetting adhesive 25 25 Stiffener Polyamide 1 mil thick Bottom side 199 Total

To prevent release of the lock due to FPC bending, use of the FPC with copper foil on bottom side is not recommended.



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